

# FDG6331L

# **Integrated Load Switch**

## **General Description**

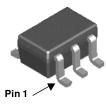
This device is particularly suited for compact power management in portable electronic equipment where 2.5V to 8V input and 0.8A output current capability are needed. This load switch integrates a small N-Channel power MOSFET (Q1) that drives a large P-Channel power MOSFET (Q2) in one tiny SC70-6 package.

## **Applications**

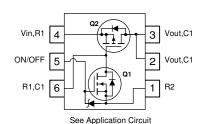
- · Power management
- Load switch

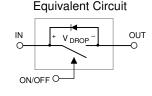
#### **Features**

- -0.8 A, -8 V.  $R_{DS(ON)} = 260 \text{ m}\Omega \text{ @ V}_{GS} = -4.5 \text{ V}$   $R_{DS(ON)} = 330 \text{ m}\Omega \text{ @ V}_{GS} = -2.5 \text{ V}$   $R_{DS(ON)} = 450 \text{ m}\Omega \text{ @ V}_{GS} = -1.8 \text{ V}$
- Control MOSFET (Q1) includes Zener protection for ESD ruggedness (>6KV Human body model)
- High performance trench technology for extremely low Rosconi
- Compact industry standard SC70-6 surface mount package









Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V <sub>IN</sub>	Gate-Source Voltage (Q2)		± 8	V
V <sub>ON/OFF</sub>	Gate-Source Voltage (Q1)		-0.5 to 8	V
I <sub>Load</sub>	Load Current - Continuous	(Note 2)	-0.8	A
	- Pulsed	(Note 2)	-2.4	
P <sub>D</sub>	Maximum Power Dissipation	(Note 1)	0.3	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		-55 to +150	°C

# **Thermal Characteristics**

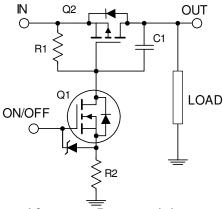
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	415	°C/W
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**Package Marking and Ordering Information** 

Device Marking	Device	Reel Size	Tape width	Quantity
.31	FDG6331L	7"	8mm	3000 units

Electric	cal Characteristics	T <sub>A</sub> = 25 °C unless otherwise noted				
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics					
BV <sub>IN</sub>	Vin Breakdown Voltage	$V_{ON/OFF} = 0 \text{ V}, I_D = -250 \mu\text{A}$	8			V
I <sub>Load</sub>	Zero Gate Voltage Drain Current	$V_{IN} = -6.4 \text{ V},  V_{ON/OFF} = 0 \text{ V}$			-1	μА
I <sub>FL</sub>	Leakage Current, Forward	$V_{ON/OFF} = 0 \text{ V},  V_{IN} = 8 \text{ V}$			100	nA
I <sub>RL</sub>	Leakage Current, Reverse	$V_{ON/OFF} = 0 \text{ V},  V_{IN} = -8 \text{ V}$			-100	nA
On Char	acteristics (Note 2)		•			•
V <sub>ON/OFF (th)</sub>	Gate Threshold Voltage	$V_{IN} = V_{ON/OFF}, I_D = -250 \mu A$	0.4	0.9	1.5	V
R <sub>DS(on)</sub>	Static Drain–Source On–Resistance (Q2)	$V_{IN} = 4.5 \text{ V},$ $I_D = -0.8 \text{ A}$ $V_{IN} = 2.5 \text{ V},$ $I_D = -0.7 \text{ A}$ $V_{IN} = 1.8 \text{ V},$ $I_D = -0.6 \text{ A}$		155 193 248	260 330 450	mΩ
$R_{\text{DS(on)}}$	Static Drain–Source On–Resistance (Q1)	$V_{IN} = 4.5 \text{ V}, \qquad I_D = 0.4 \text{A}$ $V_{IN} = 2.7 \text{ V}, \qquad I_D = 0.2 \text{ A}$		310 380	400 500	mΩ
Drain-Se	ource Diode Characteristics a	nd Maximum Ratings				
Is		aximum Continuous Drain-Source Diode Forward Current -0.25			Α	
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{ON/OFF} = 0 \text{ V}, \text{ I}_S = -0.25 \text{ A}(\text{Note 2})$			-1.2	V

# FDG6331L Load Switch Application Circuit



# External Component Recommendation:

For additional in-rush current control, R2 and C1 can be added. For more information, see application note AN1030.

Notes:
1. R<sub>aJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta JA}$  is determined by the user's board design.

<sup>2.</sup> Pulse Test: Pulse Width < 300 $\mu$ s, Duty Cycle < 2.0%.

# **Typical Characteristics**

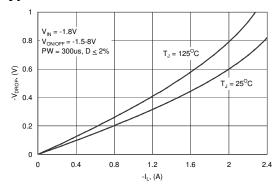


Figure 1. Conduction Voltage Drop Variation with Load Current.

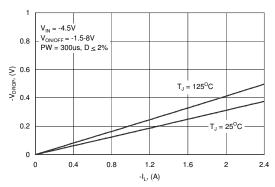


Figure 3. Conduction Voltage Drop Variation with Load Current.

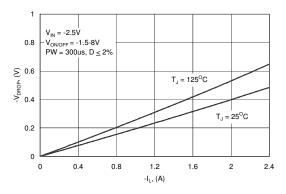


Figure 2. Conduction Voltage Drop Variation with Load Current.

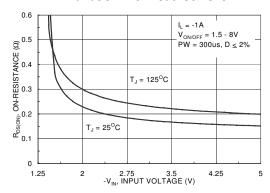


Figure 4. On-Resistance Variation With Input Voltage

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